

OCT 03 2005

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October 3, 2005

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TO: Commissioner for Patents
Attn: Fetsum Abraham
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FROM: David R. CochranOUR REF: 303.610US1TELEPHONE: 571-272-1911FAX NUMBER (571) 273-8300

*** Please deliver to Examiner Fetsum Abraham in Art Unit 2826. ***

Document(s) Transmitted: Supplemental Information Disclosure Statement (2 pages), Form 1449 (1 pg.), Authorization to charge Deposit Account 19-0743 in the amount of \$180.00 for consideration of SIDS, Communication Concerning Related Applications (1 pg.)

Total pages of this transmission, including cover letter: 5 pgs.

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In re. Patent Application of: Paul A. FarrarSerial No.: 09/382,524Filed: August 25, 1999Title: HYDROPHOBIC FOAMED INSULATORS FOR HIGH DENSITY CIRCUITSExaminer: Fetsum AbrahamGroup Art Unit: 2826Docket No.: 303.610US1RECEIVED
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By: David R. Cochran
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S/N 09/382,524

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Paul A. Farrar

Examiner: Fetsum Abraham

Serial No.: 09/382,524

Group Art Unit: 2826

Filed: August 25, 1999

Docket: 303.610US1

Title: HYDROPHOBIC FOAMED INSULATORS FOR HIGH DENSITY CIRCUITSCOMMUNICATION CONCERNING RELATED APPLICATION(S)Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450


Applicant would like to bring to the Examiner's attention the following related application(s) in the above-identified patent application:

<u>Serial/Patent No.</u>	<u>Filing Date/Issue Date</u>	<u>Attorney Docket</u>	<u>Title</u>
10/730641 6953983	December 8, 2003	1303.041US2	A SEMICONDUCTOR DEVICE COMPRISING LOW DIELECTRIC CONSTANT STI WITH SOI DEVICES
10/929632	August 30, 2004	303.681US2	POLYNORBORNENE FOAM INSULATION FOR INTEGRATED CIRCUITS
10/931510	September 1, 2004	303.603US2	PACKAGING OF ELECTRONIC CHIPS WITH AIR-BRIDGE STRUCTURES
11/216486	August 31, 2005	303.603US3	PACKAGING OF ELECTRONIC CHIPS WITH AIR-BRIDGE STRUCTURES

Continuations and divisionals may be later filed on the cases listed above, or cited to the Examiner in any previous Communication Concerning Related Applications. Applicants request that the Examiner review all continuations and divisionals of the above-listed or previously-cited patent applications before allowing the claims of the present patent application.

Respectfully submitted,
PAUL A. FARRARBy Applicant's Representatives,
SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
P.O. Box 2938
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(612) 371-2157Date 3 October 2005

By


David R. Cochran
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